Power Inductor

BPH403025W4-470T

		ECN HISTORY LIS	ST		
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	17/04/27	新 發 行	楊祥忠	黃智煒	張展耀
備					
註					

Power Inductor

BPH403025W4-470T

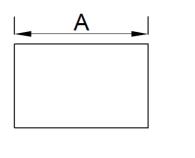
1. Features

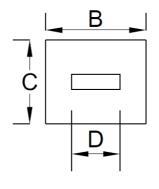
1. 100% Lead(Pb) & Halogen-Free and RoHS compliant.



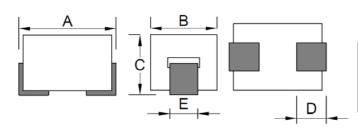


2. Dimension





CORE SIZE					
A(mm)	B(mm)	C(mm)	D(mm)		
4.00 ±0.25	3.10 ±0.15	2.50 ±0.15	1.50 ±0.15		



PRODUCT SIZE						
A(mm) B(mm) C(mn		C(mm)	D(mm)	E(mm)		
4.30~5.10	3.1 ±0.15	2.70~3.1	1.35±0.20	1.35±0.15		

3. Part Numbering



A: Series

B: Dimension

C: Material Ferrite Core D: Impedance $470=47\Omega$

E: Packaging T=Taping and Reel

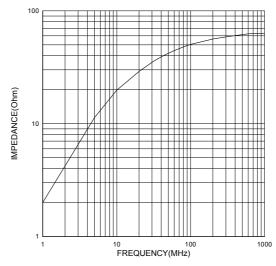
4. Specification

TAI-TECH	ELECTRICAL REQUIREMENTS 1			ELECTRICAL REQUIREMENTS 2			DCR	Rated Current	
Part Number	Impedance (Ω)	Tolerance	Test Frequency (MHz)	Impedance (Ω)	Tolerance (%)	Test Frequency (MHz)	(mΩ) Max.	∆T=40℃ TYP.	Test Frequency (MHz)
BPH403025W4-470T	25	min	25	47	±20	100	0.60	15.0	1

Note:

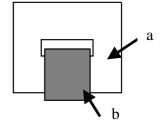
COIL SPEC: FLAT.TCW(1.25W X 0.20T)m/m

Typical Impedance v.s. Frequency Curve



5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Wire	Electroplated nickel-tin flat copper wire



6. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance Tes	st	
		CH3302,CH1320,CHA113009,Agilent E4991A,Agilent 16197A
Z(Impedance)	Refer to standard electrical characteristics list.	LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
		Heat Rated Current (Irms) will cause the coil temperature rise
		△T(°C) without core loss.
Heat Rated Current (Irms)	Approximately △T≤40°C	1.Applied the allowed DC current(keep 1 min.).
		Temperature measured by digital surface thermometer
Reliability Test	l	
Life Test		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2⋅⋅R.H, Temperature: 85°ℂ±2°ℂ Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs, keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock Vibration		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker
		Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。

Item	Performance			Test Cor	ndition	
Shock		Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec
	Appearance : No damage. Inductance : within±10% of initial value				<u> </u>	11.3 ndicular axes.
Bending	RDC : within ±15% of initial value and shall not exceed the specification value		Shall be mounted on a FR4 substrate of the following dimensions: >=0805:40x100x1.2 <0805:40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.			
Soderability	More than 95% of the terminal electrode should be covered with solder.	Solder: Temper Flux for Dip time	ature: 245± lead free: F :: 4±1sec。	g3% Cu0.5%		
Resistance to Soldering Heat	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Tem (°C)	±5(solder	Time(s)	Temperature ramp/immers and emersion 25mm/s ±6 m	rate
Terminal Strength		Preconditioning:Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to tested, apply a force (>0805 inch(2012mm):1kg, <=0805 inch(2012mm):0.5kg)to the of a device being tested. This force shall be applied for 60 +1 seconds. Also the forshall be applied gradually as not to apply a shock to the component being tested.		he device to be 5kg)to the side . Also the force		

7. Soldering and Mounting

7-1. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

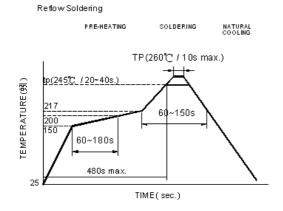
7-1.1 Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

7-1.2 Soldering Iron(Figure 2):

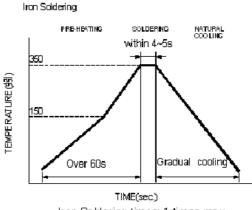
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- \bullet Preheat circuit and products to 150 $\!\!\!\!^{\circ}_{\circ}$
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355°C tip temperature (max) 1.0mm tip diameter (max)
- Limit soldering time to 4~5 sec.



Reflow times: 3 times max.

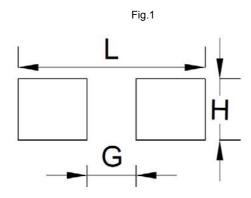
Fig.1



Iron Soldering times: 1 times max.

Fig.2

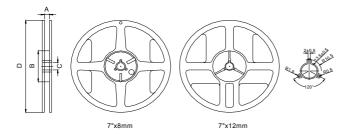
7-2. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)	
4.8	1.4	1.5	

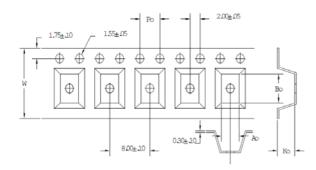
8. Packaging Information

8-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

8-2. Tape Dimension /12mm

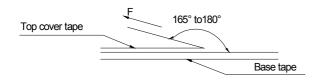


Series	Size	W(mm)	Po(mm)	Ao(mm)	Bo(mm)	Ko(mm)
ВРН	403025	12.±0.30	4.0±0.10	3.60±0.10	4.9±0.10	3.5±0.10

8-3. Packaging Quantity

Chip size	Chip / Reel	Inner box	Middle box	Carton
BPH403025	500	2000	10000	20000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

• Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



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Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO., LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

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以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

SMD BEAD CORE POWER CHOKE

樣品型號(Style/Item No.)

BPH SERIES

收件日期(Sample Receiving Date)

2017/04/17

測試期間(Testing Period)

2017/04/17 TO 2017/04/24

測試結果(Test Results) : 請見下一頁 (Please refer to next pages).





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測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鎬 / Cadmium (Cd)	mg/kg	参考IEC 62321-5 (2013),以感應耦合電 漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
鉛 / Lead (Pb)	mg/kg		2	n. d.
汞 / Mercury (Hg)	mg/kg	參考IEC 62321-4 (2013),以感應耦合電 漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	参考IEC 62321 (2008),以UV-VIS檢測. / With reference to IEC 62321 (2008) and performed by UV-VIS.	2	n. d.
多溴聯苯總和 / Sum of PBBs	mg/kg	参考IEC 62321-6 (2015),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	_	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg		5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg		5	n. d.



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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測極限值	結果 (Result)
, , , , , , , , , , , , , , , , , , ,	(0.27)	(mo thou)	(MDL)	No. 1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg			n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg	A to IRC (0001 C (0015)	5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg	參考IEC 62321-6 (2015),以氣相層析/ 質譜儀檢測. / With reference to IEC -62321-6 (2015) and performed by -GC/MS.	5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. d.
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg	参考IEC 62321-8/CD (2013),以氣相層 析儀/質譜儀檢測. / With reference to IEC 62321-8/CD (2013). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	mg/kg		50	n. d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di-(2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg		50	n. d.
鄰苯二甲酸二異丁酯 / DIBP (Di-isobutyl phthalate) (CAS No.: 84-69-5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553- 12-0; 68515-48-0)	mg/kg		50	n. d.



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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg	参考IEC 62321-8/CD (2013),以氣相層 析儀/質譜儀檢測. / With reference to IEC 62321-8/CD (2013). Analysis was performed by GC/MS.	50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	參考IEC 62321 (2008),以氣相層析/質 譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg	参考BS EN 14582 (2016),以離子層析儀 分析. / With reference to BS EN 14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(氯)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg		50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)			50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg		50	n. d.

備註(Note):

- 1. mg/kg = ppm; 0. 1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)



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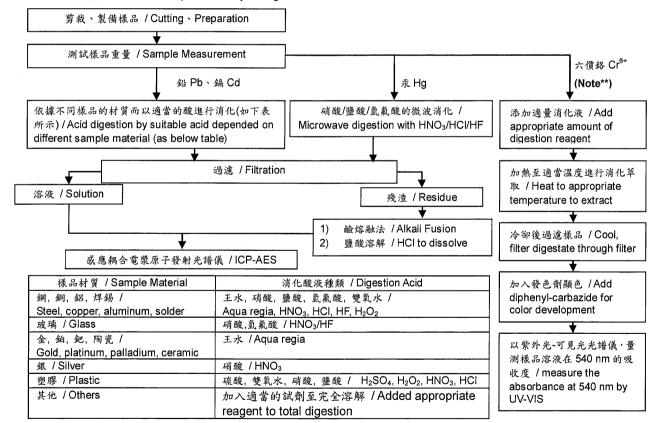
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重金屬流程圖 / Analytical flow chart of Heavy Metal (IEC 62321)

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外) /

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)

- 測試人員:王志瑋 / Technician: JR Wang
- 測試負責人:張啟興 / Supervisor: Troy Chang



Note**: (1) 針對非金屬材料加入鹼性消化液、加熱至 90~95℃ 萃取. / For non-metallic material, add alkaline digestion reagent and heat to 90~95°C.

(2) 針對金屬材料加入純水、加熱至沸騰萃取. / For metallic material, add pure water and heat to boiling



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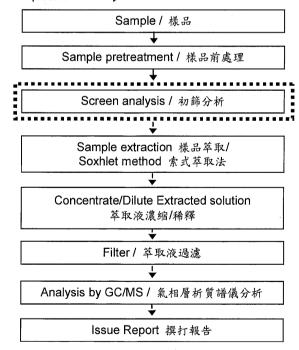
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多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

初次測試程序 / First testing process. 選擇性篩檢程序 / Optional screen process ... 確認程序 / Confirmation process - - - - →





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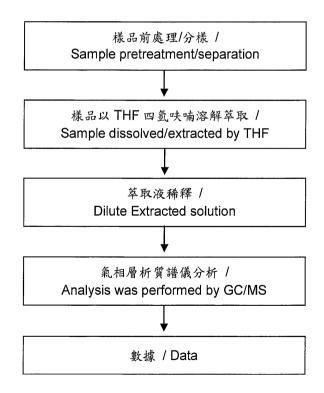
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可塑劑分析流程圖 / Analytical flow chart - Phthalate

測試人員:徐毓明 / Technician: Andy Shu

測試負責人:張啟興 / Supervisor: Troy Chang

【測試方法/Test method: IEC 62321-8】





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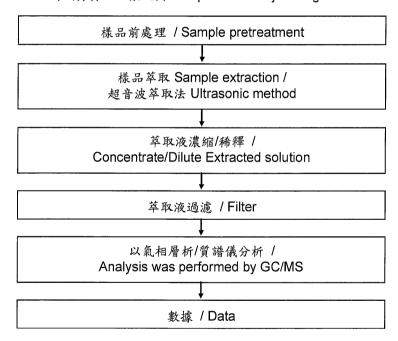
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六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang





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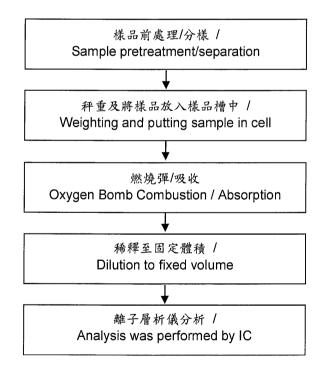
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<u> 鹵素分析流程圖 / Analytical flow chart - Halogen</u>

測試人員: 陳恩臻 / Technician: Rita Chen

測試負責人:張啟興 / Supervisor: Troy Chang





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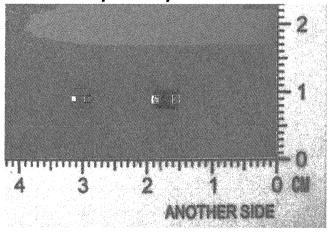
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* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

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** 報告結尾 (End of Report) **